

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info: ti.com/support
Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
Created on: 06/06/2022

Details for "SN74LV74APWRG4"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
SN74LV74APWRG4	NIPDAU	Level-1-260C-UNLIM	TI MALAYSIA A/T	PW 14	4.4x5x1.15	81.3

***Total Device Mass**
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.056345	99.998225	999982	0.069273	693
Precious Metals	Silver	7440-22-4	0.000001	0.001775	18	0.000001	0
Sub-Total			0.056346	100	1000000	0.069274	693
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.216232	80	800000	0.265846	2658
Thermoplastics	Epoxy	85954-11-6	0.054058	20	200000	0.066462	665
Sub-Total			0.27029	100	1000000	0.332308	3323
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	42.3138	97.040296	970403	52.022627	520226
Copper and Its Alloys	Iron	7439-89-6	1.1336	2.59974	25997	1.393703	13937
Copper and Its Alloys	Phosphorus	7723-14-0	0.0654	0.149985	1500	0.080406	804
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00436	0.009999	100	0.00536	54
Zinc and Its Alloys	Zinc	7440-66-6	0.0872	0.19998	2000	0.107208	1072
Sub-Total			43.60436	100	1000000	53.609304	536093
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.022446	95.11823	951182	0.027596	276
Precious Metals	Gold	7440-57-5	0.000184	0.779727	7797	0.000226	2
Precious Metals	Palladium	7440-05-3	0.000968	4.102043	41020	0.00119	12
Sub-Total			0.023598	100	1000000	0.029013	290
Mold Compound							
Other Inorganic Materials	Silica	7631-86-9	31.023373	85.000002	850000	38.141632	381416
Other Plastics and Rubber	Carbon Black	1333-86-4	0.18249	0.499999	5000	0.224362	2244
Thermoplastics	Epoxy	85954-11-6	5.292222	14.499999	145000	6.506513	65065
Sub-Total			36.498085	100	1000000	44.872507	448725
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.88462	100	1000000	1.087595	10876
Sub-Total			0.88462	100	1000000	1.087595	10876
Total			81.337299			100	1000000

Important Note
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer
TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J57098 low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.